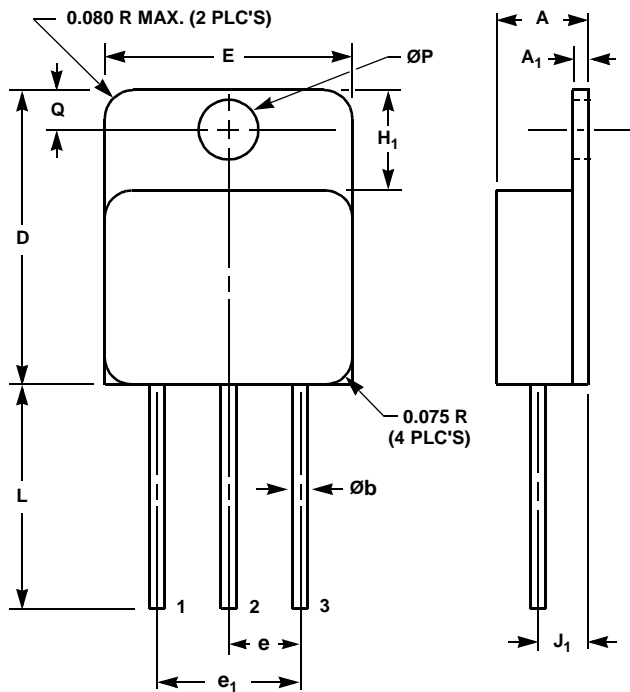


TO-258AA

3 LEAD JEDEC STYLE TO-258AA HERMETIC METAL PACKAGE



SYMBOL	INCHES		MILLIMETERS		NOTES
	MIN	MAX	MIN	MAX	
A	0.25	0.270	6.35	6.85	-
A ₁	0.03	0.045	0.89	1.14	-
$\varnothing b$	0.03	0.045	0.89	1.14	2, 3
D	0.81	0.830	20.7	21.0	-
E	0.68	0.695	17.4	17.6	-
e	0.200 TYP		5.08 TYP		4
e ₁	0.400 BSC		10.16 BSC		4
H ₁	0.27	0.290	6.86	7.36	-
J ₁	0.13	0.150	3.31	3.81	4
L	0.60	0.650	15.2	16.5	-
$\varnothing P$	0.15	0.165	3.94	4.19	-
Q	0.11	0.125	2.93	3.17	-

NOTES:

1. These dimensions are within allowable dimensions of Rev. A of JEDEC TO-258AA outline dated 2-88. Except $\varnothing b$.
2. Add typically 0.002 inches (0.05mm) for solder coating.
3. Lead dimension (without solder).
4. Position of lead to be measured 0.250 inches (6.35mm) from bottom of dimension D.
5. Die to base BeO isolated, terminals to case ceramic isolated.
6. Controlling dimension: Inch.
7. Revision 2 dated 5-98.